Final Product Change Notification | 201903004F01

Issue Date: 29-Mar-2019
Effective Date: 27-Jun-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



Management Summary
BE2 tranferring from ASEK to ATKH (grinding/sawing/marking and packing).
BE2 (back half of the Assembly process) will be enabled in ATKH.

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - BE2 process transferring (Grinding/Sawing/Marking/Packing)			

ASEK Grinding/Sawing Transferring to ATKH - NX5P3363UK

Description of Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.
BE2 (back half of the Assembly process) (grinding/sawing/marking and Packing) will be enabled in ATKH.
There's no change in Form, Fit or Function.

Reason for Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information
Samples are available upon request
Production
Planned first shipment 30-Apr-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 28-Apr-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	Support

NXP | Privacy Policy | Terms of Use

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Affected Part Number	Affected 12NC
NX5P3363UKZ	935354625012